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Atty. Dkt. No.: INFJR-0004

102788848

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jens Barrenscheen
Peter Rohm (Deceased)
Axel Aue
Jens Graf
Herman Roozenbeek



2. Name and address of receiving party(ies):

Name: Infineon Technologies AG
Street Address: St. Martin Str. 53
City/State/Zip: 81541 Munich Germany

Additional name(s) of conveying party(ies) attached?

Yes No

Additional name(s) & address(es) attached?

7-6-04 Yes No

3. Nature of conveyance:

- Assignment
- Security Agreement
- Other
- Merger
- Change of Name

Execution Date: 05/26/2004, 06/02/2004, 06/08/2004,
05/28/2004, 06/07/2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: N/A

A. Patent Application No.(s): 10/727,108

B. Patent No.(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

Patrick T. Bever, Esq.
Bever, Hoffman & Harms, LLP
2099 Gateway Place, Suite 320
San Jose, CA 95110

6. Total number of applications and patents involved: [1]

7. Total fee (37 CFR 3.41) \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number: 50-0574
(Attorney Docket No.: INFJR-0004)

DO NOT USE THIS SPACE

9. Signature.

Patrick T. Bever

July 1, 2004

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: [13]

Mail documents to be recorded with required cover sheet information to:

07/12/2004 MGETACHE 00000141 500574 10727100

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P.O. Box 1450
Alexandria, VA 22313-1450

PATENT
REEL: 015545 FRAME: 0029

ONE ADDITIONAL ASSIGNEE:

Robert Bosch GmbH
Wernerstr. 1
70469 Stuttgart-Feuerbach
Germany

ASSIGNMENT

For good and valuable consideration, I, Jens Barrenscheen, a citizen of Germany, residing at Franziskanerstr. 16, 81669 Munchen, Germany, Peter Rohm, a citizen of Germany, residing at Bistumerweg 8, 85276 Pfaffenhofen, Germany, Axel Aue, a citizen of Germany, residing at Thomas-Mann-Str. 28, 70825 Korntal-Munchlgen, Germany, Jens Graf, a citizen of Germany, residing at Goethestr. 14, 97469 Gochsheim, Germany, and Herman Roozenbeek, a citizen of The Netherlands, residing at Breslauer Str. 51, 71701 Schwleberdingen, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation, organized and existing under the laws of Germany, having its principal place of business at St. Martin Str. 53, 81541 Munich, Germany, and to **Robert Bosch GmbH**, a corporation, organized and existing under the laws of Germany, having its principal place of business at Wernerstr. 1, 70469 Stuttgart-Feuerbach, Germany, hereinafter "Assignees", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and filed December 2, 2003, Serial Number 10/727,108 entitled:

"ARRANGEMENT COMPRISING A FIRST SEMICONDUCTOR CHIP AND A SECOND SEMICONDUCTOR CHIP CONNECTED THERETO"

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignees may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignees, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignees, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignees, its successors, assigns and legal representatives; and

Covenant with said Assignees, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: 
Jens Barrenscheen

DATE: May 26, 2004

SIGNATURE: _____
Peter Rohm

DATE: _____

SIGNATURE: _____ DATE: _____
Axel Aue

SIGNATURE: _____ DATE: _____
Jens Graf

SIGNATURE: _____ DATE: _____
Herman Roozenbeek

ASSIGNMENT

For good and valuable consideration, I, Jens Barrenscheen, a citizen of Germany, residing at Franziskanerstr. 16, 81669 Munchen, Germany, Peter Rohm, a citizen of Germany, residing at Bistumerweg 8, 85276 Pfaffenjofen, Germany, Axel Aue, a citizen of Germany, residing at Thomas-Mann-Str. 28, 70825 Korntal-Munchlngen, Germany, Jens Graf, a citizen of Germany, residing at Goethestr. 14, 97469 Gochsheim, Germany, and Herman Roozenbeek, a citizen of The Netherlands, residing at Breslauer Str. 51, 71701 Schwleberdingen, Germany, hereinafter individually or collectively referred to as "Assignor";

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SIGNATURE: _____ DATE: _____
Jens Barrenscheen

SIGNATURE: Angela Roh DATE: 2.6.2004
Peter Rohm

SIGNATURE: _____ DATE: _____
Axel Aue

SIGNATURE: _____ DATE: _____
Jens Graf

SIGNATURE: _____ DATE: _____
Herman Roozenbeek

SIGNING BY EXECUTOR(TRIX) ON BEHALF OF DECEASED INVENTOR
(37 CFR 1.42 and 1.43)

I, ANGELA ROHM, hereby declare that I am a citizen of
Germany residing at:
Bismarckweg 8
D-85276 Pfaffenhofen
(mailing address)

and that I am executing and signing the declaration to which this is
attached as executor(trix) of the last will and testament of:

Country of Citizenship: Peter Rohm
Germany

That, upon information and belief, I aver those facts that the inventor
is required to state.

Date: 2. 6. 2004
Angela Rohm
Signature of executor(trix)

ASSIGNMENT

For good and valuable consideration, I, Jens Barrenscheen, a citizen of Germany, residing at Franziskanerstr. 16, 81669 Munchen, Germany, Peter Rohm, a citizen of Germany, residing at Bistumerweg 8, 85276 Pfaffenjofen, Germany, Axel Aue, a citizen of Germany, residing at Thomas-Mann-Str. 28, 70825 Korntal-Munchlgen, Germany, Jens Graf, a citizen of Germany, residing at Goethestr. 14, 97469 Gochsheim, Germany, and Herman Roozenbeek, a citizen of The Netherlands, residing at Breslauer Str. 51, 71701 Schwleberdingen, Germany, hereinafter individually or collectively referred to as "Assignor";

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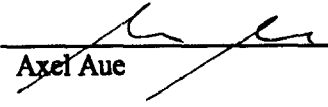
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SIGNATURE: _____ DATE: _____
Jens Barrenscheen

SIGNATURE: _____ DATE: _____
Peter Rohm

SIGNATURE:  DATE: 8.06.04
Axel Aue

SIGNATURE: _____ DATE: _____
Jens Graf

SIGNATURE: _____ DATE: _____
Herman Roozenbeek

ASSIGNMENT

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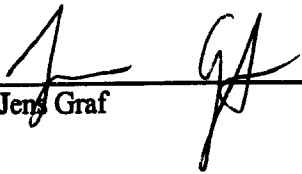
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SIGNATURE: _____ DATE: _____
Jens Barrenscheen

SIGNATURE: _____ DATE: _____
Peter Rohm

SIGNATURE: _____ DATE: _____
Axel Aue

SIGNATURE:  _____ DATE: 28.5.2004
Jens Graf

SIGNATURE: _____ DATE: _____
Herman Roozenbeek

ASSIGNMENT

For good and valuable consideration, I, Jens Barrenscheen, a citizen of Germany, residing at Franziskanerstr. 16, 81669 Munchen, Germany, Peter Rohm, a citizen of Germany, residing at Bistumerweg 8, 85276 Pfaffenjofen, Germany, Axel Aue, a citizen of Germany, residing at Thomas-Mann-Str. 28, 70825 Korntal-Munchlngen, Germany, Jens Graf, a citizen of Germany, residing at Goethestr. 14, 97469 Gochsheim, Germany, and Herman Roozenbeek, a citizen of The Netherlands, residing at Breslauer Str. 51, 71701 Schwleberdingen, Germany, hereinafter individually or collectively referred to as "Assignor";

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Jens Barrenscheen

SIGNATURE: _____ DATE: _____
Peter Rohm

SIGNATURE: _____ DATE: _____
Axel Aue

SIGNATURE: _____ DATE: _____
Jens Graf

SIGNATURE: *Herman Roozenbeek* DATE: 7. June 2004
Herman Roozenbeek